



RF360  
Europe GmbH

## Data sheet

### SAW filter

Automotive telematics  
WLAN 2G

Part number: B2653  
Ordering code: B39242B2653P810

Date: March 10, 2021  
Version: 2.0

DCN: 80-PA243-550 Rev. A

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RF360 Europe GmbH  
Anzinger Straße 13  
81671 Munich, Germany

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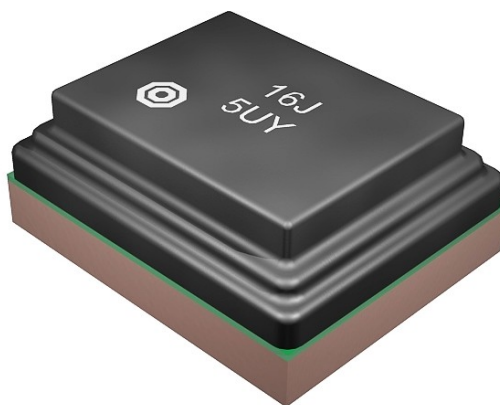
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## 1 Application

- WLAN 2G downlink: 2450 MHz (pass band 100 MHz)
- Very low insertion loss

## 2 Features

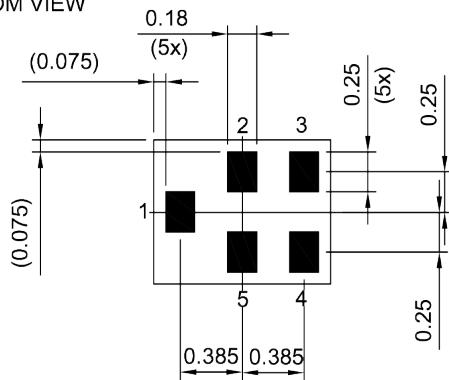
- Package size  $1.1 \pm 0.1$  mm  $\times$   $0.9 \pm 0.1$  mm
- Package height 0.45 mm (max.)
- Approximate weight 2 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Filter surface passivated
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 2a (MSL2a)
- AEC-Q200 qualified component family  
(Grade 3:  $-40$  °C to  $+85$  °C)



**Figure 1:** Picture of component with example of product marking.

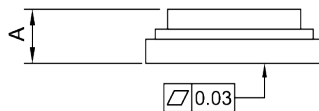
### 3 Package

BOTTOM VIEW

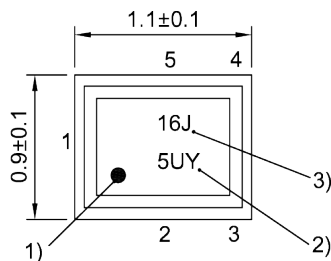


Pad and pitch tolerance  $\pm 0.05$

SIDE VIEW

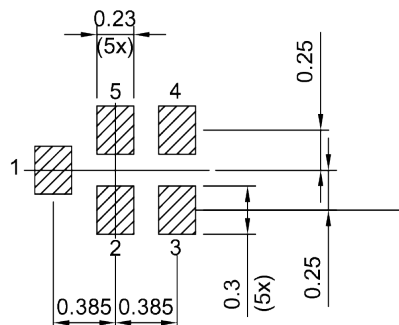


TOP VIEW



- 1) Marking for pad number 1
- 2) Example of encoded lot number
- 3) Example of encoded filter type number

Land pattern  
THRU VIEW



Landing pad tolerance  $-0.02$

**Figure 2:** Drawing of package with package height A = 0.45 mm (max.). See Sec. Package information (p. 18).

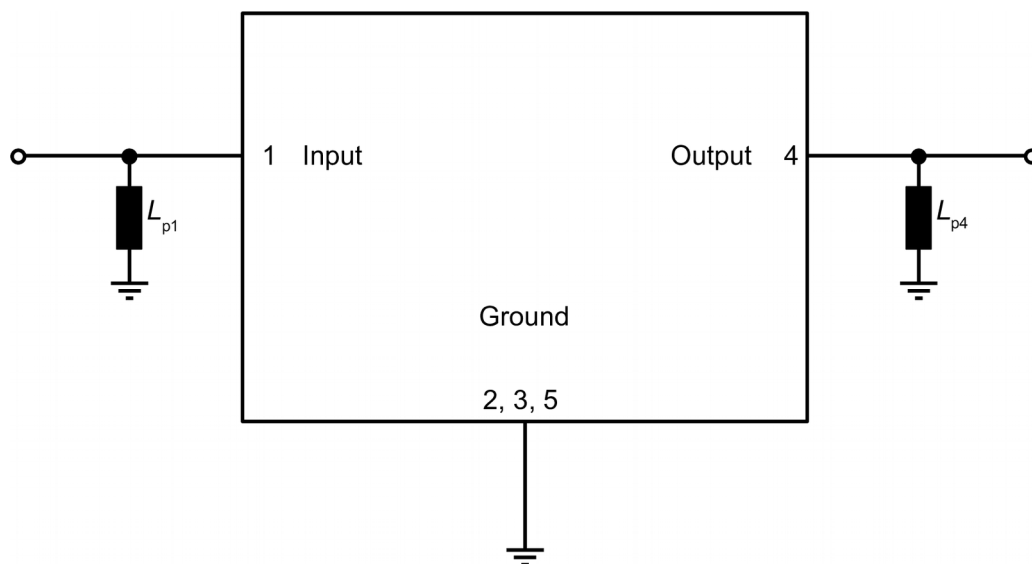
### 4 Pin configuration

- 1 Input
- 4 Output
- 2, 3, 5 Ground

## 5 Matching circuit

■  $L_{p1} = 3.8 \text{ nH}$

■  $L_{p4} = 4.1 \text{ nH}$



**Figure 3:** Schematic of matching circuit.

## 6 Characteristics

Temperature range for specification	$T_{\text{SPEC}}$	= -40 °C ... +85 °C
Input terminating impedance	$Z_{\text{IN}}$	= 50 $\Omega$ // 3.8 nH <sup>1)</sup>
Output terminating impedance	$Z_{\text{OUT}}$	= 50 $\Omega$ // 4.1 nH <sup>1)</sup>

Characteristics			min. for $T_{\text{SPEC}}$	typ. @ +25 °C	max. for $T_{\text{SPEC}}$	
<b>Center frequency</b>		$f_{\text{C}}$	—	2450	—	MHz
<b>Maximum insertion attenuation</b>		$\alpha_{\text{max}}$				
	2400 ... 2500	MHz	—	0.9	1.0 <sup>2)</sup>	dB
	2400 ... 2500	MHz	—	0.9	1.3	dB
<b>Maximum VSWR</b>		$\text{VSWR}_{\text{max}}$				
@ input port	2400 ... 2500	MHz	—	1.5	2.0	
@ output port	2400 ... 2500	MHz	—	1.5	2.0	
<b>Minimum attenuation</b>		$\alpha_{\text{min}}$				
	100 ... 1000	MHz	25	32	—	dB
	1000 ... 2300	MHz	12	15	—	dB
	2600 ... 4800	MHz	15	19	—	dB
	4800 ... 5000	MHz	30	33	—	dB
	5000 ... 6000	MHz	17	24	—	dB

<sup>1)</sup> See Sec. Matching circuit (p. 6).

<sup>2)</sup> Valid for typical temperature  $T = +25$  °C.

## 7 Maximum ratings

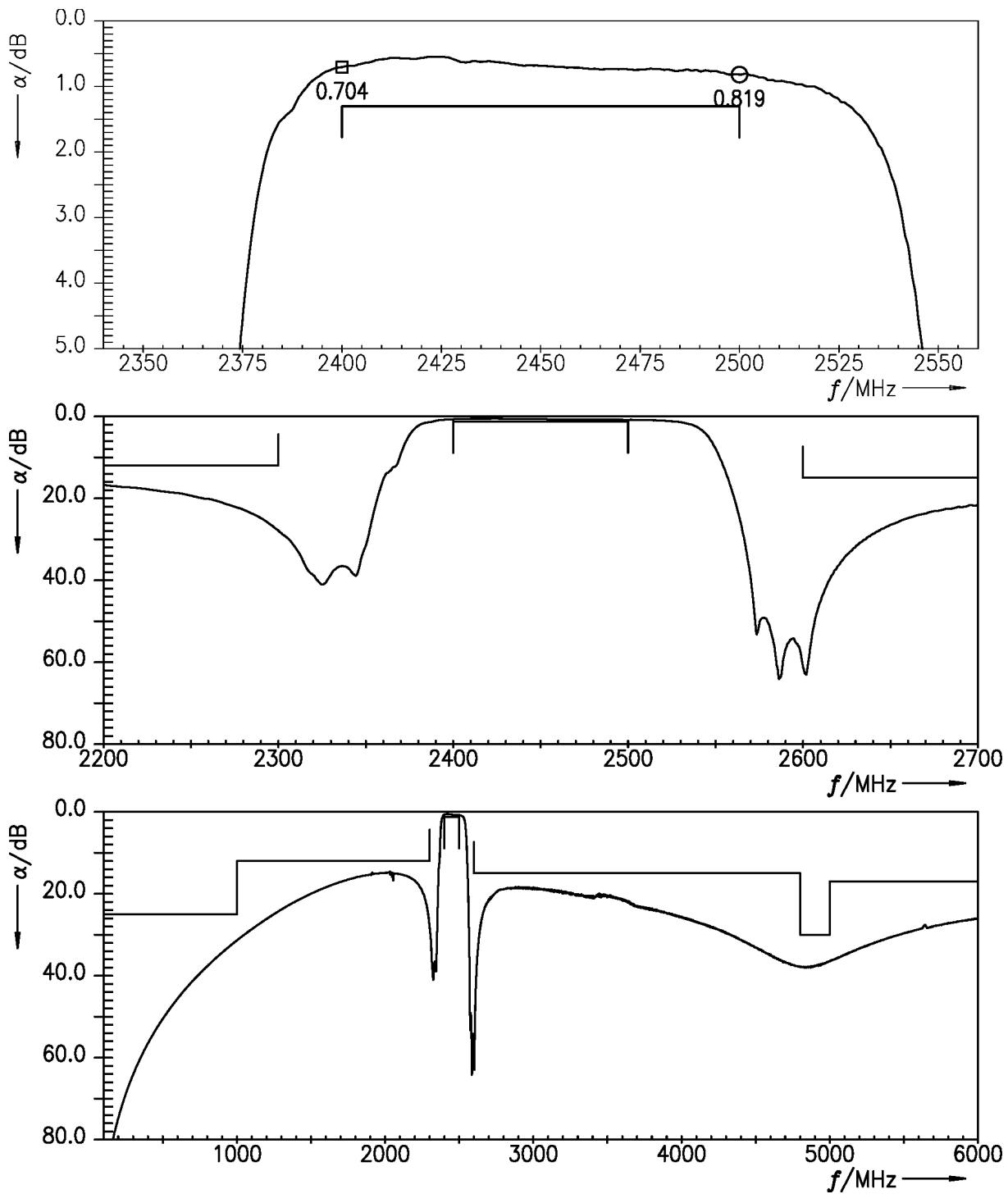
Operable temperature	$T_{OP} = -40\text{ °C} \dots +85\text{ °C}$	
Storage temperature	$T_{STG}^{2)} = -40\text{ °C} \dots +85\text{ °C}$	
DC voltage	$ V_{DC} ^{1)} = 0\text{ V (max.)}$	
Input power	$P_{IN}$	
@ input port: 2400 ... 2500 MHz	24 dBm	Continuous wave for 10000 h @ 55 °C.
@ output port: 2400 ... 2500 MHz	24 dBm	Continuous wave for 10000 h @ 55 °C.

<sup>1)</sup> In case of applied DC voltage blocking capacitors are mandatory.

<sup>2)</sup> Not valid for packaging material. Storage temperature for packaging material is -25 °C to +40 °C.



## 8 Transmission coefficient



**Figure 4:** Attenuation.

## 9 Reflection coefficients

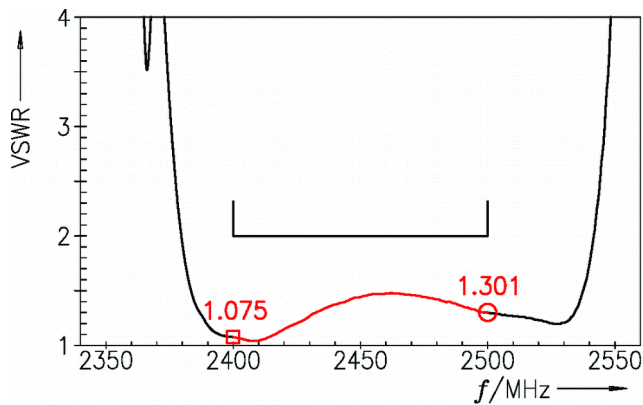


Figure 5: Reflection coefficient at input port.

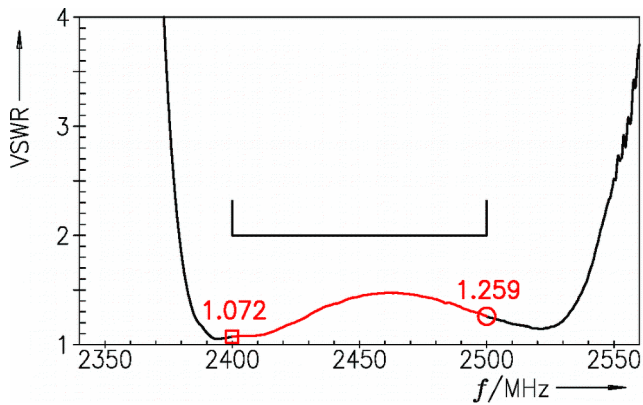
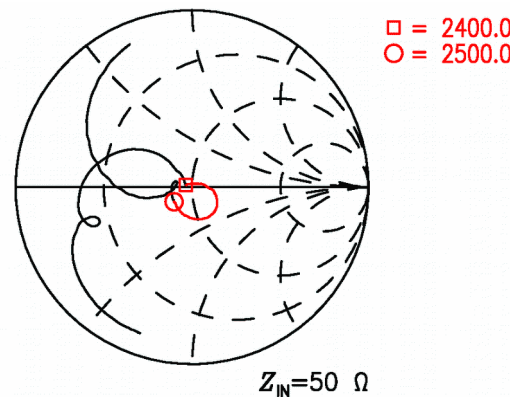
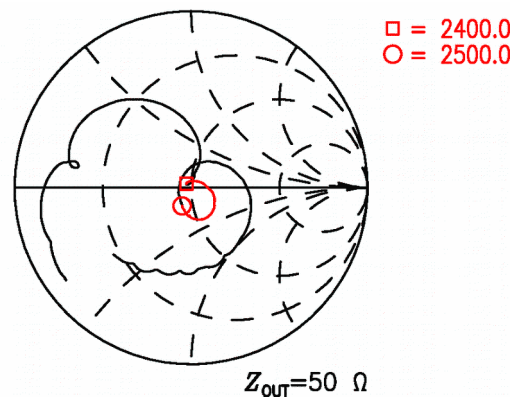
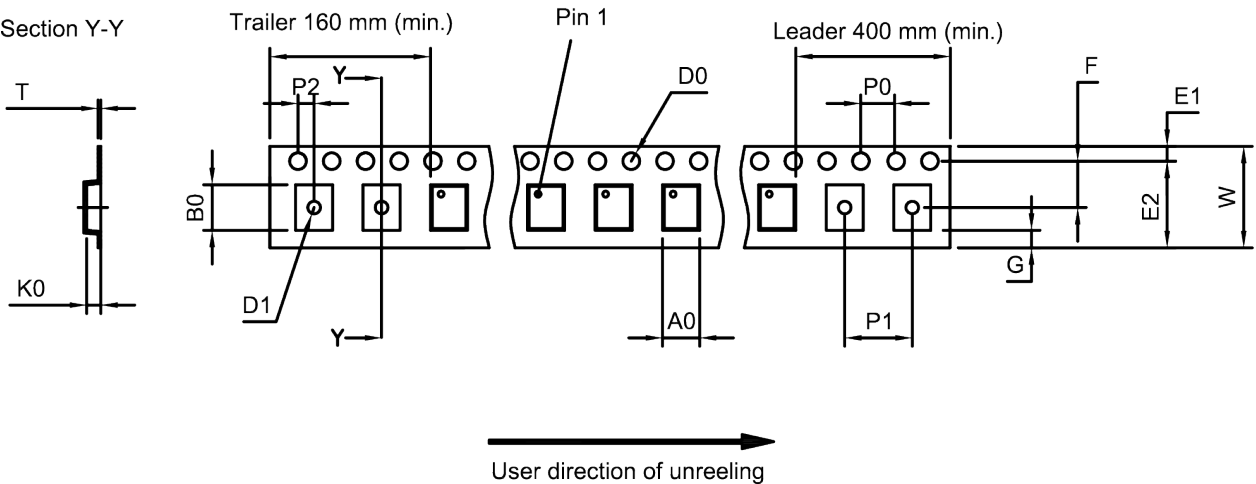


Figure 6: Reflection coefficient at output port.



10 Packing material

10.1 Tape

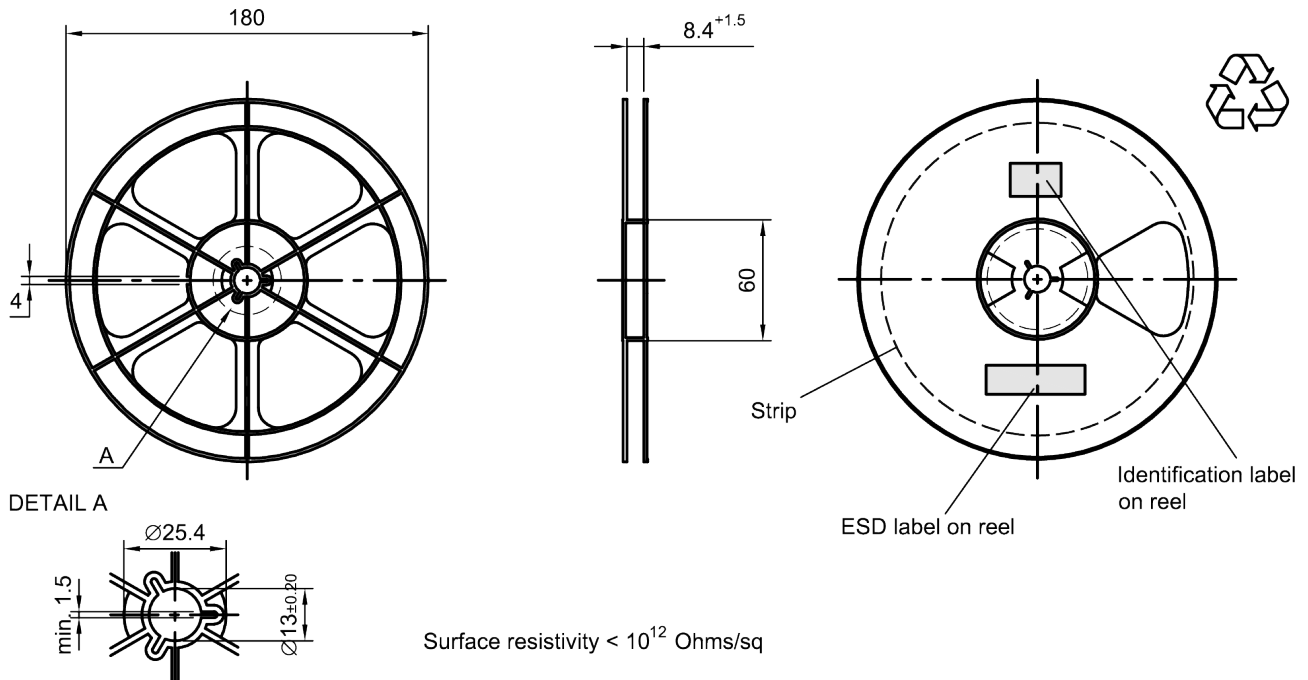


**Figure 7:** Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

A <sub>0</sub>	1.02±0.05 mm	E <sub>2</sub>	6.25 mm (min.)	P <sub>1</sub>	2.0±0.1 mm
B <sub>0</sub>	1.22±0.05 mm	F	3.5±0.05 mm	P <sub>2</sub>	2.0±0.05 mm
D <sub>0</sub>	1.55±0.05 mm	G	–	T	0.25±0.03 mm
D <sub>1</sub>	0.55±0.1 mm	K <sub>0</sub>	0.6±0.05 mm	W	8.0+0.3/-0.1 mm
E <sub>1</sub>	1.75±0.1 mm	P <sub>0</sub>	4.0±0.1 mm		

**Table 1:** Tape dimensions.

## 10.2 Reel with diameter of 180 mm



**Figure 8:** Drawing of reel (first-angle projection) with diameter of 180 mm.

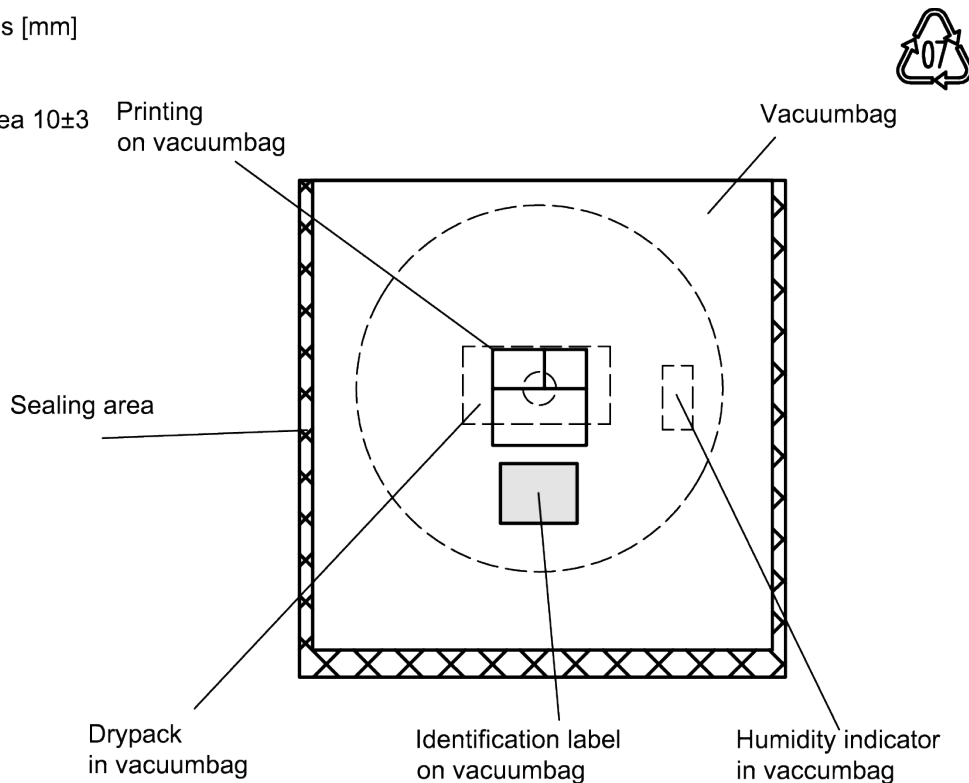
Dimensions [mm]

X = 220+5

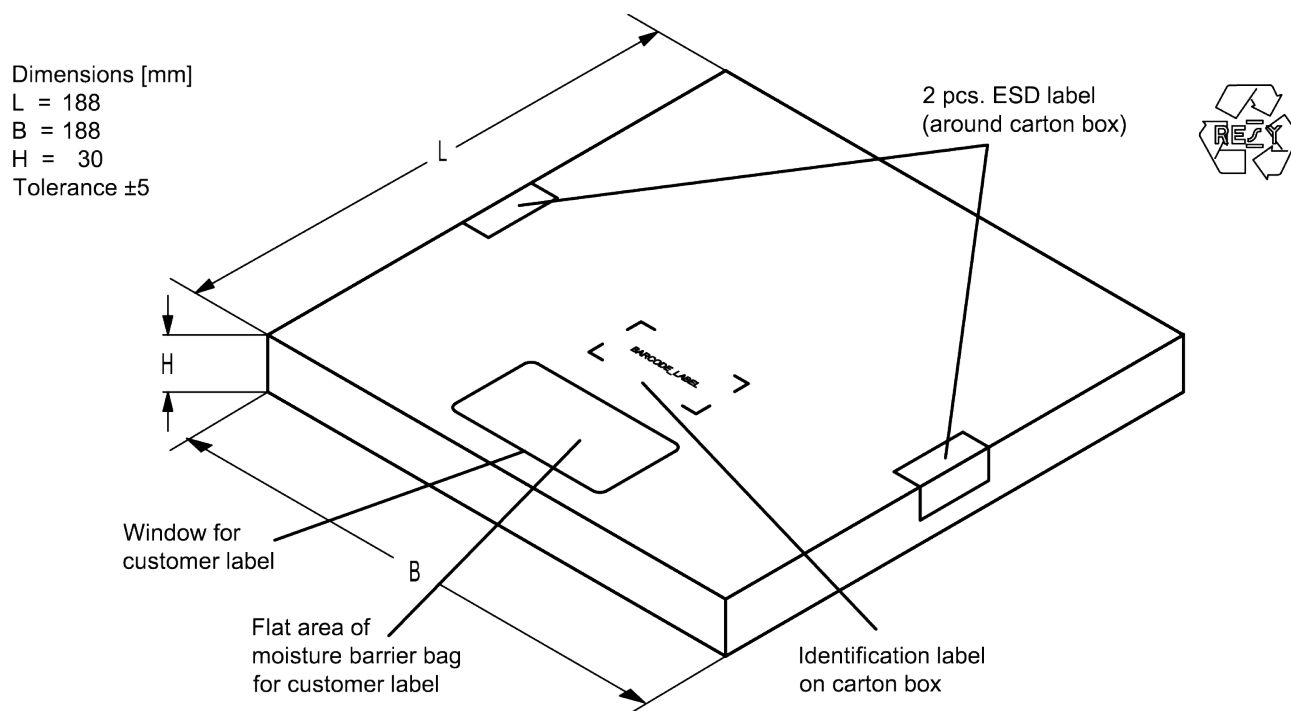
Y = 235+5

Sealing area 10±3

Printing  
on vacuumbag



**Figure 9:** Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.



**Figure 10:** Drawing of folding box for reel with diameter of 180 mm.

## 11 Marking

Products are marked with product type number and lot number encoded according to Table 2:

### ■ Type number:

The 4 digit type number of the ordering code, e.g., B3xxxxB**1234**xxxx,  
is encoded by a special BASE32 code into a 3 digit marking.

Example of decoding type number marking on device in decimal code.  
**16J**  $\Rightarrow$  **1234**  
 $1 \times 32^2 + 6 \times 32^1 + 18 (=J) \times 32^0 =$  **1234**  
 The BASE32 code for product type B2653 is 2JX.

### ■ Lot number:

The last 5 digits of the lot number, e.g., **12345**,  
are encoded based on a special BASE47 code into a 3 digit marking.

Example of decoding lot number marking on device in decimal code.  
**5UY**  $\Rightarrow$  **12345**  
 $5 \times 47^2 + 27 (=U) \times 47^1 + 31 (=Y) \times 47^0 =$  **12345**

Adopted BASE32 code for type number			
Decimal value	Base32 code	Decimal value	Base32 code
0	0	16	G
1	1	17	H
2	2	18	J
3	3	19	K
4	4	20	M
5	5	21	N
6	6	22	P
7	7	23	Q
8	8	24	R
9	9	25	S
10	A	26	T
11	B	27	V
12	C	28	W
13	D	29	X
14	E	30	Y
15	F	31	Z

Adopted BASE47 code for lot number			
Decimal value	Base47 code	Decimal value	Base47 code
0	0	24	R
1	1	25	S
2	2	26	T
3	3	27	U
4	4	28	V
5	5	29	W
6	6	30	X
7	7	31	Y
8	8	32	Z
9	9	33	b
10	A	34	d
11	B	35	f
12	C	36	h
13	D	37	n
14	E	38	r
15	F	39	t
16	G	40	v
17	H	41	\
18	J	42	?
19	K	43	{
20	L	44	}
21	M	45	<
22	N	46	>
23	P		

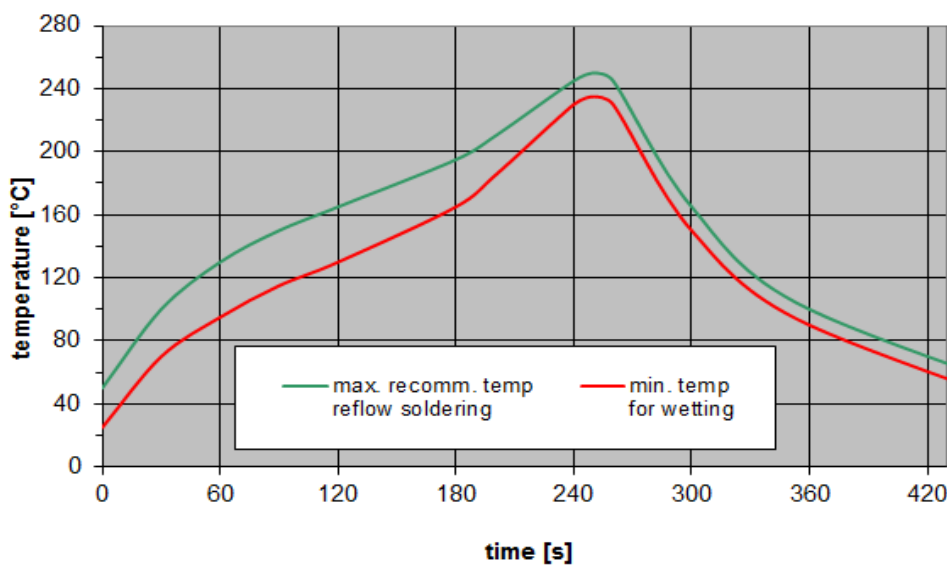
**Table 2:** Lists for encoding and decoding of marking.

## 12 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3<sup>rd</sup> edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
$T > 220\text{ °C}$	30 s to 70 s
$T > 230\text{ °C}$	min. 10 s
$T > 245\text{ °C}$	max. 20 s
$T \geq 255\text{ °C}$	–
peak temperature $T_{\text{peak}}$	250 °C +0/-5 °C
wetting temperature $T_{\text{min}}$	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature $T$	measured at solder pads

**Table 3:** Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).



**Figure 11:** Recommended reflow profile for convection and infrared soldering – lead-free solder.

### 13 ESD protection of SAW filters

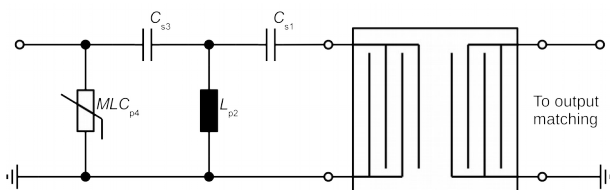
SAW filters are **E**lectro **S**tatic **D**ischarge sensitive devices. To reduce the probability of damages caused by ESD, special matching topologies have to be applied.

In general, “ESD matching” has to be ensured at that filter port, where electrostatic discharge is expected.

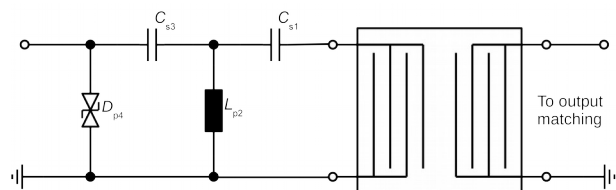
Electrostatic discharges predominantly appear at the antenna input of RF receivers. Therefore, only the input matching of the SAW filter has to be designed to short circuit or to block the ESD pulse.

Below three figures show recommended “ESD matching” topologies.

For wide band filters the high-pass ESD matching structure needs to be at least of 3<sup>rd</sup> order to ensure a proper matching for any impedance value of antenna and SAW filter input. The required component values have to be determined from case to case.

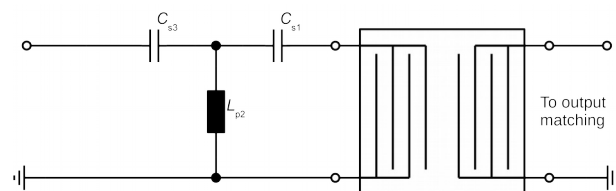


**Figure 12:** MLC varistor plus ESD matching.



**Figure 13:** Suppressor diode plus ESD matching.

In cases where minor ESD occur, following simplified “ESD matching” topologies can be used alternatively.



**Figure 14:** 3<sup>rd</sup> order high-pass structure for basic ESD protection.

In all three figures the shunt inductor  $L_{p2}$  could be replaced by a shorted microstrip with proper length and width. If this configuration is possible depends on the operating frequency and available PCB space.

Effectiveness of the applied ESD protection has to be checked according to relevant industry standards or customer specific requirements.

For further information, please refer to RF360 Application report: “**ESD protection for SAW filters**”. This report can be found under <https://rffe.qualcomm.com>.



## 14 Annotations

### 14.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

### 14.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

## 15 Cautions and warnings

### 15.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under <https://rfe.qualcomm.com/>.

### 15.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

### 15.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

### 15.4 Package information

#### Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

#### Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Dimensions do not include burrs.

#### Projection method

Unless otherwise specified first-angle projection is applied.

## 16 Important notes

The following applies to all products named in this publication:

1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application**. As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
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